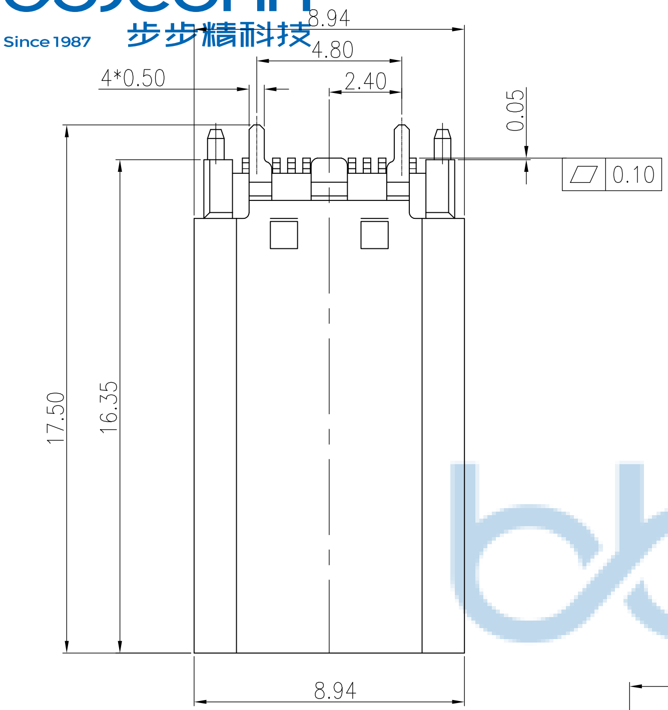
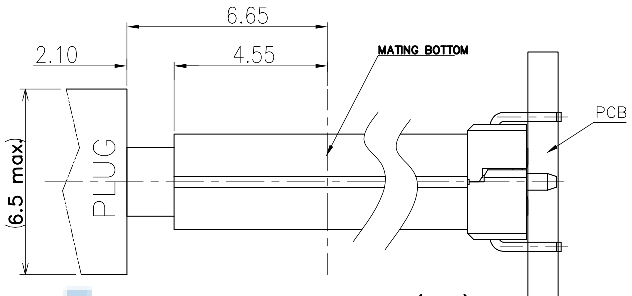
REV	ECN NO	CONTENT	DATE	ENGINEER
A0		INITIAL RELEASE	/	SGF





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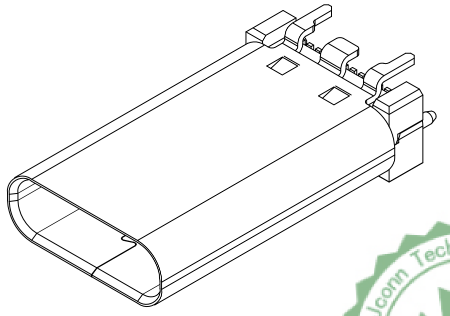

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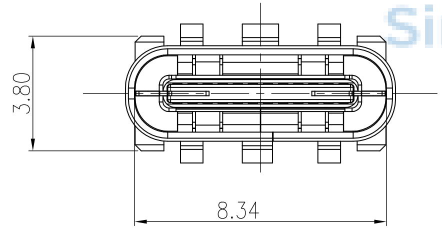

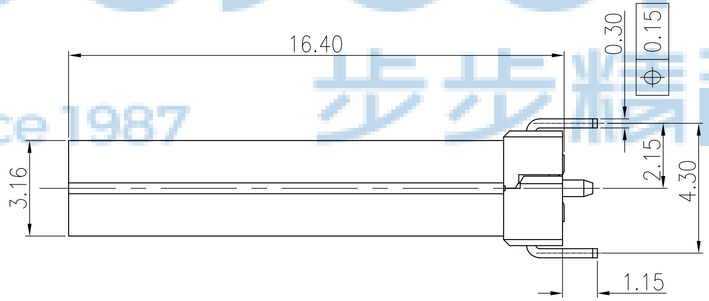

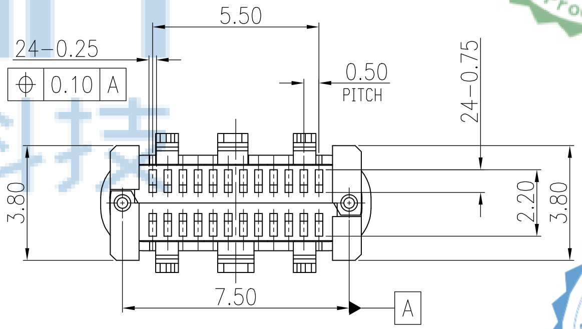

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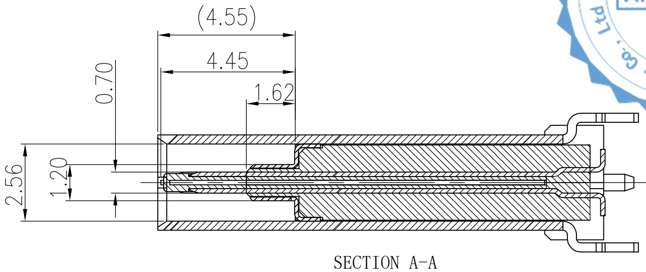
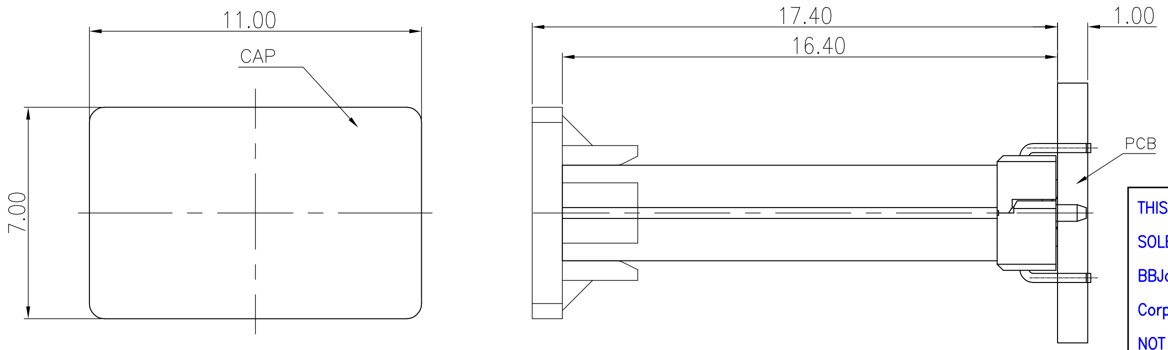


SECTION A-A



CAP ASSEMBLY AND MOUTING CONDITION (REF.)

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.X: ±0.38	X°: ±3°
.XX: ±0.25	.X°: ±2°
.XXX: ±0.13	.XX°: ±1°

NAME: TYPE-C 24P 母座 立贴 四脚插 带柱 端子SMT H=16.4 不锈钢外壳 编带

APPD	JM_Zheng
CHKD	LYX
DR	SGF

PJ NO: 126-224-240002-H8G
SIZE:A4
DRW NO:
FINISH:SEE NOTES
MAT'L:SEE NOTES
SCALE:N/A
REV:A0
UNIT:mm
PAGE:1/3

PDWG NO: 0482-1

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REV	ECN NO	CONTENT	DATE	ENGINEER
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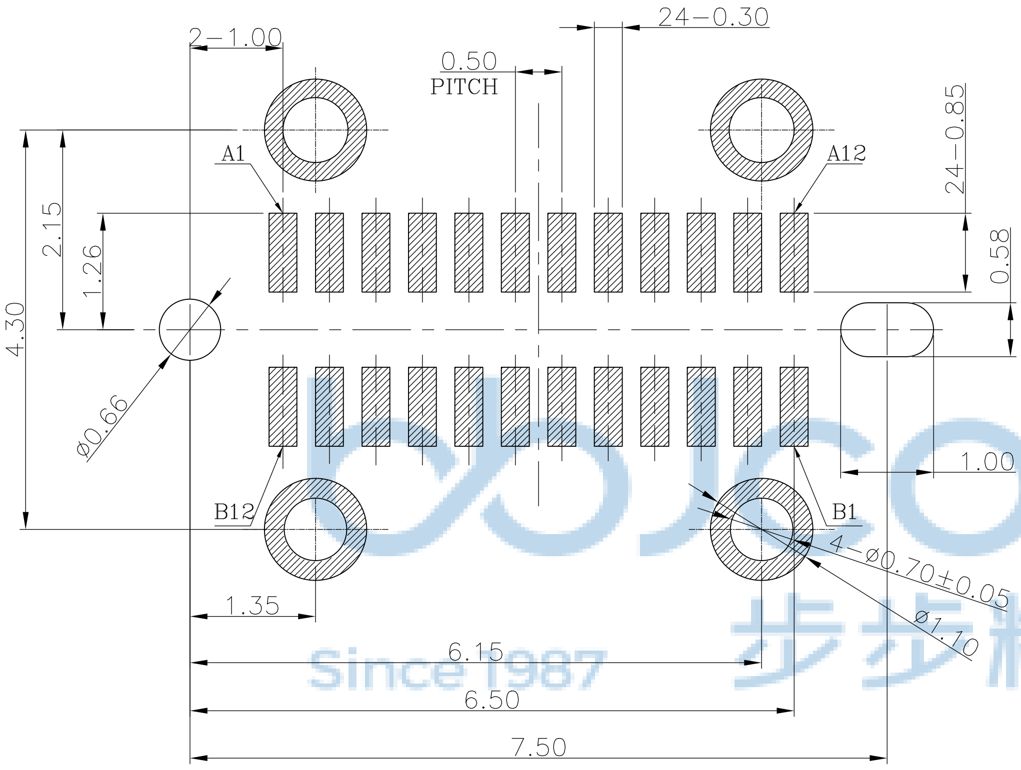

RECOMMENDED P.C.B. LAYOUT (T:1.00mm)
TOLERANCE UNSPECIFIED ±0.05mm
SCALE: 2:1

NOTES:

1. ELECTRICAL CHARACTERISTICS :
   - 1-1. CONTACT CURRENT RATING:
     5.0 A FOR VBUS PIN AND ITS CORRESPONDING GND PIN.
     0.25 A MIN FOR ALL OTHER CONTACTS.
   - 1-2. CONTACT RESISTANCE: INITIAL 40 mΩ Max.
     AFTER 50 mΩ Max.
   - 1-3. DIELECTRIC WITHSTANDING VOLTAGE : 100 VRMS AC MIN.
   - 1-4. INSULATION RESISTANCE: 100 MEGOHMS MIN.
2. MECHANICAL CHARACTERISTICS:
   - 2-1. CONNECTOR INSERTION FORCE: 5~20N.
     AT A MAXIMUN RATE OF 12.5MM PER SECOND.
   - 2-2. CONNECTOR EXTRACTION FORCE: 8~20N FORM 1000 CYCLES
     6~20N FORM 1000 to 10000 CYCLES
   - 2-3. DURABILITY: 10000 CYCLES.
   - 2-4. OPERATING TEMPERATURE: -55°C TO +85°C
3. DIMENSIONS ARE IN MILLIMETERS, BRACKETED DIMENSIONS ARE INCHES EQUIVALENTS.
4. RECOMMENED PROCESS: IR REFLOW 260°C, 10 SECONDS.
5. THE CONNECTOR IS ROHS COMPLIANT.

PIN	SIGNAL NAME	PIN	SIGNAL N
A1	GND	B12	GND
A2	SSTXp1	B11	SSRXp1
A3	SSTXn1	B10	SSRXn1
A4	VBUS	B9	VBUS
A5	CC1	B8	SBU2
A6	Dp1	B7	Dn2
A7	Dn1	B6	Dp2
A8	SBU1	B5	CC2
A9	VBUS	B4	VBUS
A10	SSRXn2	B3	SSTXn2
A11	SSRXp2	B2	SSTXp2
A12	GND	B1	GND

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⑥	TOP CONTACT	1 SET	COPPER ALLOY	50u" MIN. Ni UNDER PLATING. 80u" MIN. MATTE TIN PLATING ON SOLDER AREA GOLD PLATING ON CONTACT AREA. SEE PART NO.
⑤	BOTTOM CONTACT	1 SET	COPPER ALLOY	
④	SHIELDING PLATE	1 PCS	STAINLESS	50u" MIN. SOLDERABLE Ni PLATING OVERALL.
③	HOUSING	1 PCS	THERMOPLASTIC.	UL94V-0
②	SHELL	1 PCS	STAINLESS	50u" MIN. SOLDERABLE Ni PLATING OVERALL.
①	TOP SHELL	1 PCS	STAINLESS	50u" MIN. SOLDERABLE Ni PLATING OVERALL.
ITFM	PART NAMF	OTY	MATFRIAL	RFMARK

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NAME: TYPE-C 24P 母座 立贴 四脚插 带柱
端子SMT H=16.4 不锈钢外壳 编带

APPD JM_Zheng
CHKD LYX
DR SGF

PJ NO: 126-224-240002-H8G
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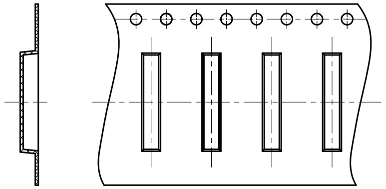
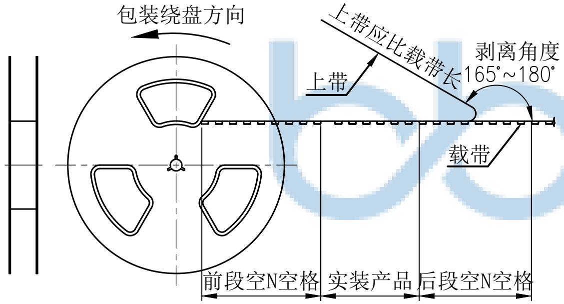
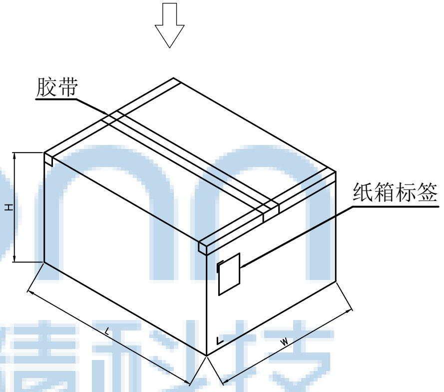
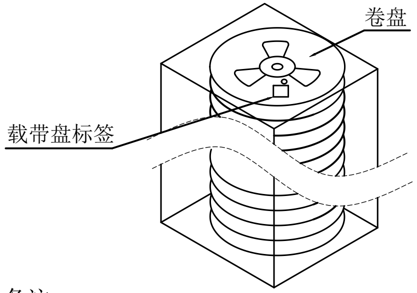






纸箱规格：W345*L345*H230MM



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备注：

1、包装数量：150/PCS/卷，10卷/箱。
2、包装袋长度：每卷前后各空10-20个空格，中间包装。
3、材质：
   载体：聚丙烯（PS），阻抗10^{6-9} Ω
   上带：聚乙烯（PET），阻抗10^{6-11} Ω
   卷盘：聚苯乙烯。

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